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**Semiconductor devices – Micro-electromechanical devices –
Part 34: Test methods for MEMS piezoresistive pressure-sensitive device on
wafer**

INTERNATIONAL
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MICRO-ELECTROMECHANICAL DEVICES –**
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FDIS	Report on voting
47F/328/FDIS	47F/333/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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- withdrawn,
- replaced by a revised edition, or
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SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part 34: Test methods for MEMS piezoresistive pressure-sensitive device on wafer

1 Scope

This part of IEC 62047 describes test conditions and test methods of electric character, static performances and thermal performances for MEMS pressure-sensitive devices. This document applies to test for both open and closed loop piezoresistive MEMS pressure devices on wafer.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61193-2, *Quality assessment systems – Part 2: Selection and use of sampling plans for inspection of electronic components and packages*

IEC 60747-14-3, *Semiconductor devices – Part 14-3: Semiconductor sensors – Pressure sensors*